Supplementary Materials: Comparison of Ultrasonic Welding and Thermal Bonding for the Integration of Thin Film Metal Electrodes in Injection Molded Polymeric Lab-on-Chip Systems for Electrochemistry

Marco Matteucci, Arto Heiskanen, Kinga Zór, Jenny Emnéus and Rafael Taboryski

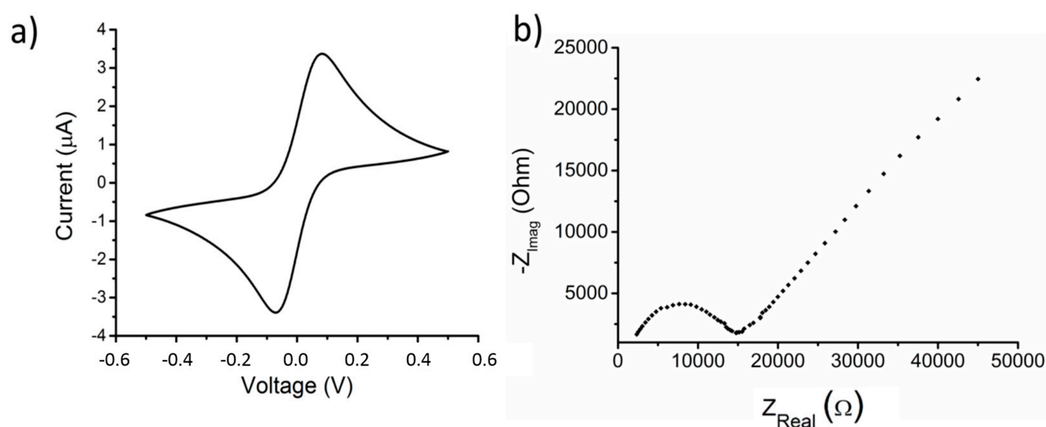

Figure S1. Representative data for (**a**) electrical cyclic voltammetry (CV) and (**b**) electrochemical impedance spectroscopic (EIS) characterization of Au electrodes in a chip thermally bonded at T = 125 °C, F = 1 kN, t = 10 min.